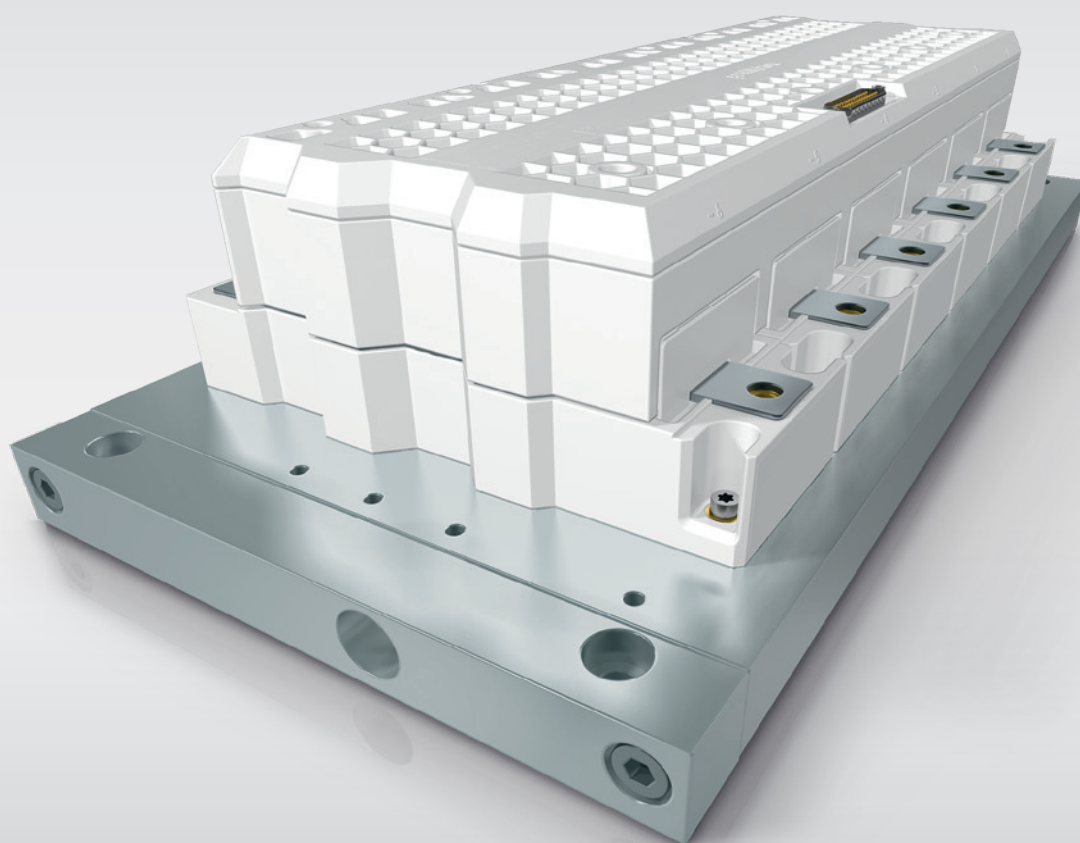


Most Powerful IPM on the Market



SKiiP[®] 4

500kW up to 2.1MW



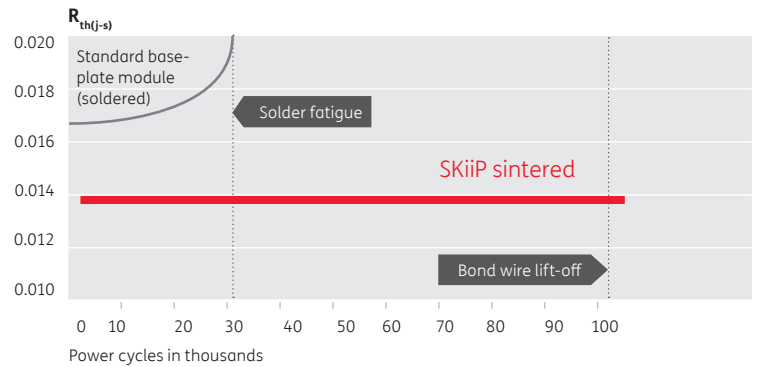
Extremely high power cycling capability

Sinter technology

- 5% improvement of total thermal resistance thanks to sinter layer
- Unbreakable joint between chips and DCB
- High melting point at > 900°C (4 x higher than standard solder) no solder fatigue

IGBT 4 and CAL4F technology

- T_j , max = 175°C, the key to higher current capability



Highest reliability

New pressure contact design

- Low-inductive design
- More homogeneous current distribution

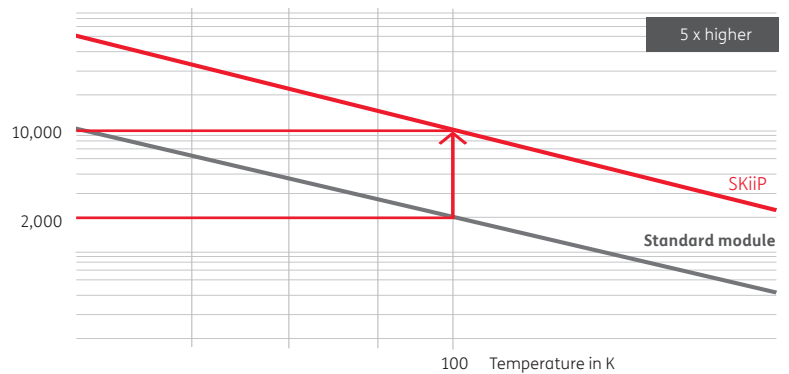
Robust mechanical design

- High ruggedness against mechanical shock and vibration

Advanced driver design

- Enhanced FIT rate by ASIC technology
- Switching and sensor signals safety isolated

Thermal cycling performance 5 x higher temperature cycling



Benefits of SKiIP 4 driver

Function and self-protection

- Digital signal transmission for high signal integrity and noise immunity
- All switching and sensor signals safety isolated
- New 1500V_{DC} version for typical PV-solar power applications
- Parallel operation for increased output power
- Multi-output stage for variable switching behaviour and low over-voltage
- Integrated protection functions
- CANopen interface with detailed error recorder and parameterisation functionality

SKiIP 4 product range

- 1200V / 1700V SKiIP 4



IGBT half bridges in parallel

$I_{C@Ts} = 25^\circ\text{C}$

3

1800A

4

2400A

6

3600A

Key features

500kW up to 2.1MW

3 in 1: driver with protection functions, semiconductors & cooling

Integrated current, voltage and temperature sensor

Sintered chips, no solder fatigue

High power cycling capability

SKiIP technology / Single-sided sintering technology

 We are close to our customers
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